ABSOLUTE MAXIMUM RATINGS

V _{CC} to GND (Note 1)0.3V to +13.2V V _{EE} to GND (Note 1)+0.3V to -13.2V	6-Pin SOT23 (derate 8.7mW/°C above +70°C)691mW		
V _{CC} to V _{EE} (Note 1)+22V TIN, SHDN to GND0.3V to +7V TOUT to GND (SHDN = GND)±13.2V	Operating Temperature Range40°C to +85°C Junction Temperature+150°C Storage Temperature Range65°C to +150°C		
Output Short-Circuit to GND DurationContinuous	Lead Temperature (soldering, 10s)+300°C		

Note 1: V_{CC} and V_{EE} can have maximum magnitudes of 13.2V, but their absolute difference cannot exceed 22V.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

ELECTRICAL CHARACTERISTICS

(V_{CC} = +7.5V to +12V, V_{EE} = -7.5V to -12V, T_A = T_{MIN} to T_{MAX}, unless otherwise noted. Typical values are at V_{CC} = +10V, V_{EE} = -10V, and T_A = +25°C.) (Note 2)

PARAMETER	SYMBOL	CONDITIONS	MIN	ТҮР	МАХ	UNITS
DC CHARACTERISTICS						<u>.</u>
Positive Supply Voltage	V _{CC}		7.5		12	V
Negative Supply Voltage	VEE		-12		-7.5	V
Positive Supply Current	ICC	$V_{\overline{SHDN}} = +5V$			250	μA
Negative Supply Current	IEE	$V_{\overline{SHDN}} = +5V$	-125			μA
Shutdown Supply Current		$V_{\overline{SHDN}} = 0$		±0.4	±10	μA
INPUT LOGIC (TIN, SHDN)	<u>.</u>					
Input Logic Threshold Low	VIL				0.8	V
Input Logic Threshold High	VIH		2.4			V
Input Leakage				±0.01	±1	μA
TIN Input Hysteresis				100		mV
TRANSMITTER OUTPUT	<u>.</u>					
		V_{CC} = 7.5V, V_{EE} = -7.5V, R_L = 3k Ω	±5			V
Output Voltage Swing	Vtout	$V_{CC} = 6V, V_{EE} = -6V, R_L = 3k\Omega$	±3.7			V
Output Resistance	RTOUT	$V_{CC} = V_{EE} = 0$, $V_{TOUT} = \pm 2V$	300			Ω
Output Short-Circuit Current				±35	+60	mA
Output Leakage Current	Ітоит	$V_{TOUT} = \pm 12V$; $V_{CC} = 0$ or $V_{CC} = \pm 10V$, $V_{EE} = -10V$; $\overline{SHDN} = GND$			±100	μA
TIMING CHARACTERISTICS	-					<u>.</u>
Maximum Data Rate		$\begin{aligned} R_L &= 3k\Omega, \\ C_L &= 1000pF \end{aligned}$	460			kbps
Transmitter Skew	t _{TS}	ItpHL - tpLHI, Figure 1		100		ns
Transition-Region Slew Rate		$ \begin{array}{l} {\sf R}_L = 3 {\sf k} \Omega \mbox{ to } 7 {\sf k} \Omega, \\ {\sf C}_L = 300 {\sf p} {\sf F} \mbox{ to } 1000 {\sf p} {\sf F}, \mbox{ measured from } -3 {\sf V} \\ {\sf to } +3 {\sf V} \mbox{ or } +3 {\sf V} \mbox{ to } -3 {\sf V}, \\ {\sf V}_{\rm CC} = +10 {\sf V}, \mbox{ V}_{\rm EE} = -10 {\sf V}, \mbox{ T}_{\rm A} = +25 {\rm ^{\circ}C} \end{array} $	6		30	V/µs
Transmitter Enable Time	t _{EN}			2		μs

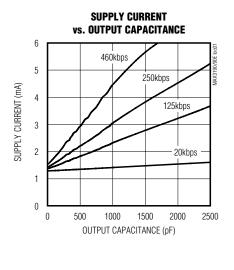
ELECTRICAL CHARACTERISTICS (continued)

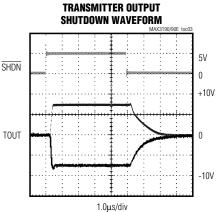
(V_{CC} = +7.5V to +12V, V_{EE} = -7.5V to -12V, T_A = T_{MIN} to T_{MAX}, unless otherwise noted. Typical values are at V_{CC} = +10V, V_{EE} = -10V, and T_A = +25°C.) (Note 2)

PARAMETER	SYMBOL	CONDITIONS	MIN	ТҮР	MAX	UNITS
ESD PROTECTION (MAX3190E)						
		Human Body Model		±15		
TOUT		IEC 1000-4-2 Contact Discharge		±8		kV
		IEC 1000-4-2 Air-Gap Discharge		±15]

Note 2: All devices are 100% tested at $T_A = +25^{\circ}$ C. All limits over temperature are guaranteed by design.

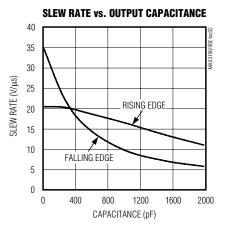
 $(V_{CC} = +10V, V_{EE} = -10V, R_L = 3k\Omega, T_A = +25^{\circ}C, unless otherwise noted.)$

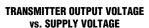


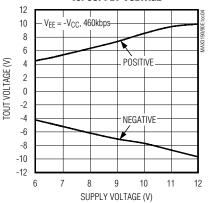












MAX3190/MAX3190E

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PIN

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_Pin Description

NAME FUNCTION Active-Low Shutdown. Pull low to SHDN reduce the supply current and to force TOUT into a high-impedance state. GND Ground TIN TTL/CMOS Transmitter Input TOUT RS-232 Transmitter Output Negative Supply Voltage VFF Vcc Positive Supply Voltage

Detailed Description

The MAX3190/MAX3190E are EIA/TIA-232 transmitters that convert CMOS/TTL logic levels to RS-232 signals. They operate on \pm 7.5V to \pm 12V supplies and feature enhanced electrostatic discharge protection (see *ESD Protection*). The MAX3190/MAX3190E guarantee a 460kbps data rate with worst-case loads of 3k Ω in parallel with 1000pF. The MAX3190/MAX3190E invert the TOUT signal relative to TIN (standard RS-232). The transmitter input does not have a pullup resistor and should be connected to GND if unused.

Shutdown The MAX3190/MAX3190E feature a shutdown input. Drive SHDN low to reduce the supply current to 1µA (max). Shutdown also forces TOUT into a high-impedance state, allowing the signal line to be safely controlled by other transmitters. Drive SHDN high for normal operation.

ESD Protection

As with all Maxim devices, ESD protection structures are incorporated on all pins to protect against ESD encountered during handling and assembly. The MAX3190E's transmitter output has extra protection against static electricity. Maxim has developed state-of-the-art structures enabling this pin to withstand ESD up to ± 15 kV without damage or latch-up. The MAX3190E's transmitter output is characterized for protection to the following limits:

- ±15kV using the Human Body Model
- ±8kV using the Contact Discharge method specified in IEC 1000-4-2
- ±15kV using the Air-Gap Discharge method specified in IEC 1000-4-2

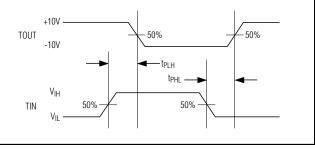


Figure 1. Transmitter Propagation-Delay Timing

Human Body Model

Figure 2 shows the Human Body Model, and Figure 3 shows the current waveform it generates when discharged into a low impedance. This model consists of a 100pF capacitor charged to the ESD voltage of interest, and then discharged into the test device through a $1.5 k\Omega$ resistor.

IEC 1000-4-2

The IEC 1000-4-2 standard covers ESD testing and performance of finished equipment; it does not specifically refer to ICs. The MAX3190E enables the design of equipment that meets the highest level (Level 4) of IEC 1000-4-2 without the need for additional ESD-protection components. The major difference between tests done using the Human Body Model and IEC 1000-4-2 is higher peak current in IEC 1000-4-2. Because series resistance is lower in the IEC 1000-4-2 model, the ESD withstand voltage measured to this standard is generally lower than that measured using the Human Body. Figure 4 shows the IEC 1000-4-2 model, and Figure 5

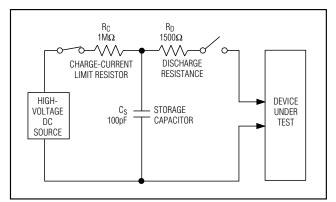


Figure 2. Human Body ESD Test Model

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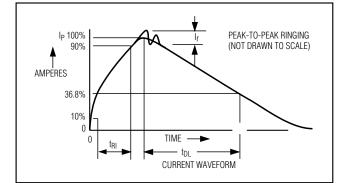


Figure 3. Human Body Model Current Waveform

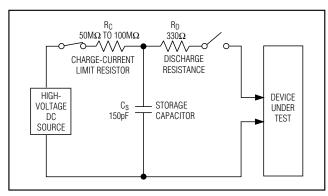


Figure 4. IEC 1000-4-2 ESD Test Model

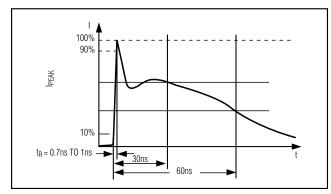


Figure 5. IEC 1000-4-2 Generator Current Waveform

shows the current waveform for the $\pm 8kV$ IEC 1000-4-2 Level 4 ESD Contact Discharge test. The Air-Gap test involves approaching the device with a charged probe. The Contact Discharge method connects the probe to the device before the probe is energized.

Power-Supply Decoupling

In most circumstances, 0.1µF bypass capacitors are adequate for power-supply decoupling. Connect the bypass capacitors as close to the IC as possible.

Applications Information

Power-Supply Sources

The MAX3190/MAX3190E require $\pm 7.5V$ to $\pm 12V$ dual supplies. For applications where these supply voltages are not present, a DC-DC converter must be added. Due to the MAX3190/MAX3190E's low current consumption, a charge pump can provide the proper supply voltages and requires a minimal amount of board space and cost.

When using another RS-232 device containing an internal unregulated charge pump (Tables 1 and 2), the MAX3190/MAX3190E may be powered from the internal charge pump (Figure 6). This eliminates the need for additional external DC-DC converters to generate the required $\pm 7.5V$ to $\pm 12V$ dual supplies. The MAX3190/MAX3190E are specifically designed to be used with Maxim's RS-232 products listed in Tables 1 and 2. Competitive RS-232 devices' charge pumps typically do not have the capability to power these devices.

The MAX3190/MAX3190E can be operated from $\pm 6V$ to $\pm 7.5V$ supplies. In this condition, the devices are guaranteed to be RS-232-compatible (TOUT $\geq +3.7V$).

For applications that have $\pm 4.5V$ to $\pm 6V$ supplies available, please refer to the MAX3188/MAX3189 or MAX3188E/MAX3189E data sheet.

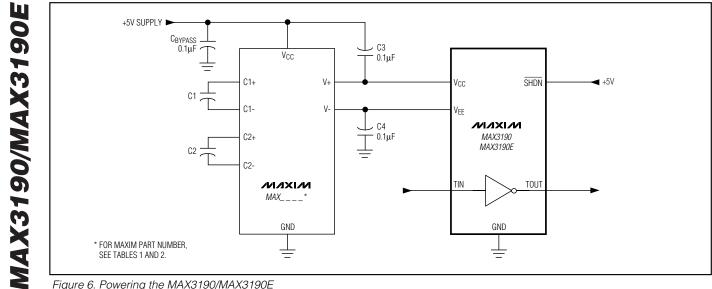


Figure 6. Powering the MAX3190/MAX3190E

Table 1. RS-232 Devices with InternalUnregulated Charge Pumps of ±10V(typical)

PART NUMBER	NO. OF TX/RX	DATA RATE (kbps)
MAX200	5/0	120
MAX201	2/2	120
MAX202	2/2	64
MAX203	2/2	120
MAX204	4/0	120
MAX205	5/5	120
MAX206	4/3	120
MAX207	5/3	120
MAX208	4/4	120
MAX209	3/5	120
MAX211	4/5	120
MAX213	4/5	120
MAX220	2/2	120
MAX221	1/1	250
MAX222	2/2	200
MAX223	4/5	120
MAX225	5/5	120
MAX230	5/0	120
MAX231	2/2	120
MAX232	2/2	120
MAX232A	2/2	200
MAX233A	2/2	200
MAX233	2/2	120
MAX234	4/0	120
MAX235	5/5	120
MAX236	4/3	120
MAX237	5/3	120
MAX238	4/4	120
MAX239	3/5	120
MAX240	5/5	120
MAX241	4/5	120
MAX242	2/2	200
MAX243	2/2	200
MAX244	8/10	120
MAX248	8/8	120
MAX249	6/10	120

Table 2. ±15kV ESD-Protected RS-232Devices with Internal Unregulated ChargePumps of ±10V (typical)

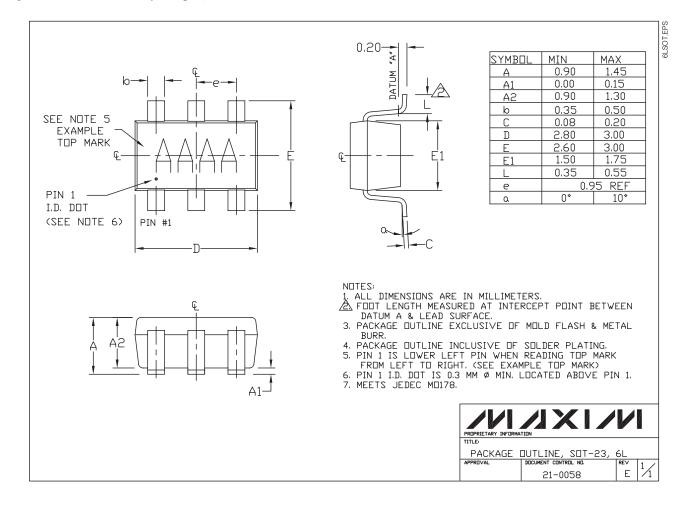
PART NUMBER	NO. OF TX/RX	DATA RATE (kbps)
MAX202E	2/2	64
MAX203E	2/2	120
MAX205E	5/5	120
MAX206E	4/3	120
MAX207E	5/3	120
MAX208E	4/4	120
MAX211E	4/5	120
MAX213E	4/5	120
MAX221E	1/1	250
MAX241E	4/5	120

Chip Information

TRANSISTOR COUNT: 75 PROCESS: CMOS

Package Information

(The package drawing(s) in this data sheet may not reflect the most current specifications. For the latest package outline information, go to **www.maxim-ic.com/packages**.)



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8

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